

NON-HERMETIC ENCAPSULANT REMOVAL FOR MODULE REWORK

Abstract

A depolymerization cleaning solution, and method of using such solution, for removing undesirable thermoset polymer sealants residing on electronic components to provide such components with a clean seal surface for a subsequent rework process. The depolymerization cleaning solution includes a premixed metal hydroxide or amino onium salt saturated solution having a surfactant. It is particularly useful for the localized deposition and removal of thermoset polymer sealants, such as polysiloxanes, within sealband areas of the components, which have been applied on such components with different levels of chemical inertness. The material set and method disclosed in the present invention are the basis for a low cost electronic package adhesive rework process.